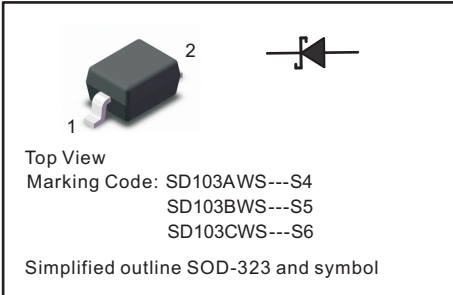


Schottky Barrier Diode

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



FEATURES

- ◆ Low Forward Voltage Drop
- ◆ Guard Ring Construction for Transient Protection
- ◆ Negligible Reverse Recovery Time
- ◆ Low Capacitance

MECHANICAL DATA

- ◆ Case: SOD-323
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 5.48mg / 0.00019oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Parameter	Symbols	SD103AWS	SD103BWS	SD103CWS	Units
Peak Repetitive Reverse Voltage	V_{RRM}	40	30	20	V
RMS reverse voltage	V_{RMS}	28	21	14	V
Working Peak Reverse Voltage	V_{DC}	40	30	20	V
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	13			A
Maximum Instantaneous Forward Voltage $I_F=20mA$ $I_F=200mA$	V_F	0.37 0.60			V
Power Dissipation	P_D	200			mW
Reverse current SD103AWS, $V_R=30V$ SD103BWS, $V_R=20V$ SD103CWS, $V_R=10V$	I_R	5 – –	– 5 –	– – 5	μA
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	300			°C/W
Reverse voltage $I_R=100\mu A$	$V_{(BR)R}$	SD103AW SD103BW SD103CW	40 30 20		V
Reverse recovery time $I_F=I_R=200mA, I_{rr}=0.1 \times I_R, R_L=100\Omega$	t_{rr}	10			ns
Forward Continuons Current	I_{FM}	350			mA
Total capacitance $V_R=0V, f=1MHz$	C_{tot}	50			pF
Junction temperature	T_j	125			°C
Storage temperature	T_{stg}	-55 ~ +150			°C

Fig.1 Power Derating Curve

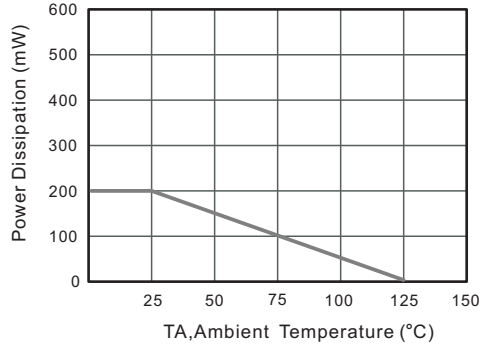


Fig.2 Typical Reverse Characteristics

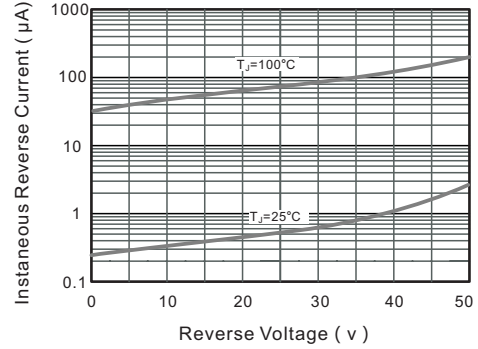


Fig.3 Forward Characteristics

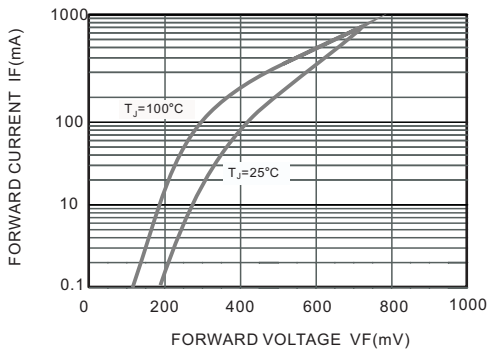


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current

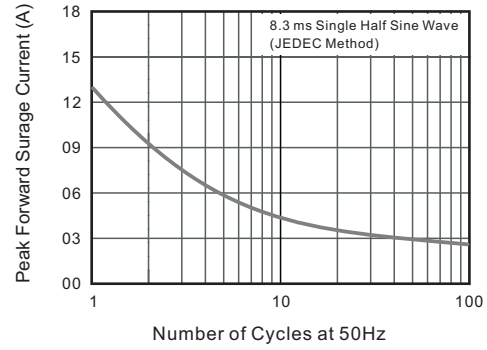


Fig.5 Typical Junction Capacitance

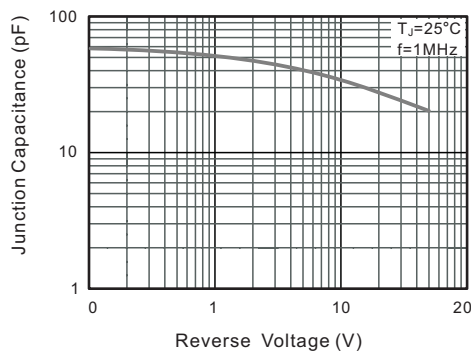
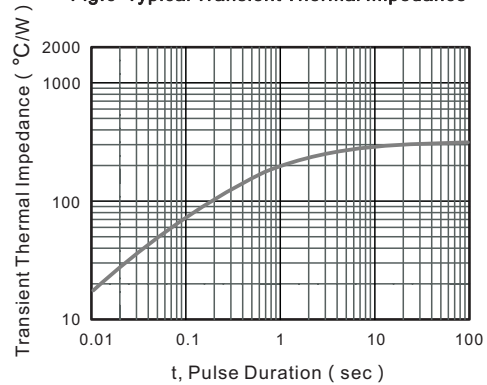


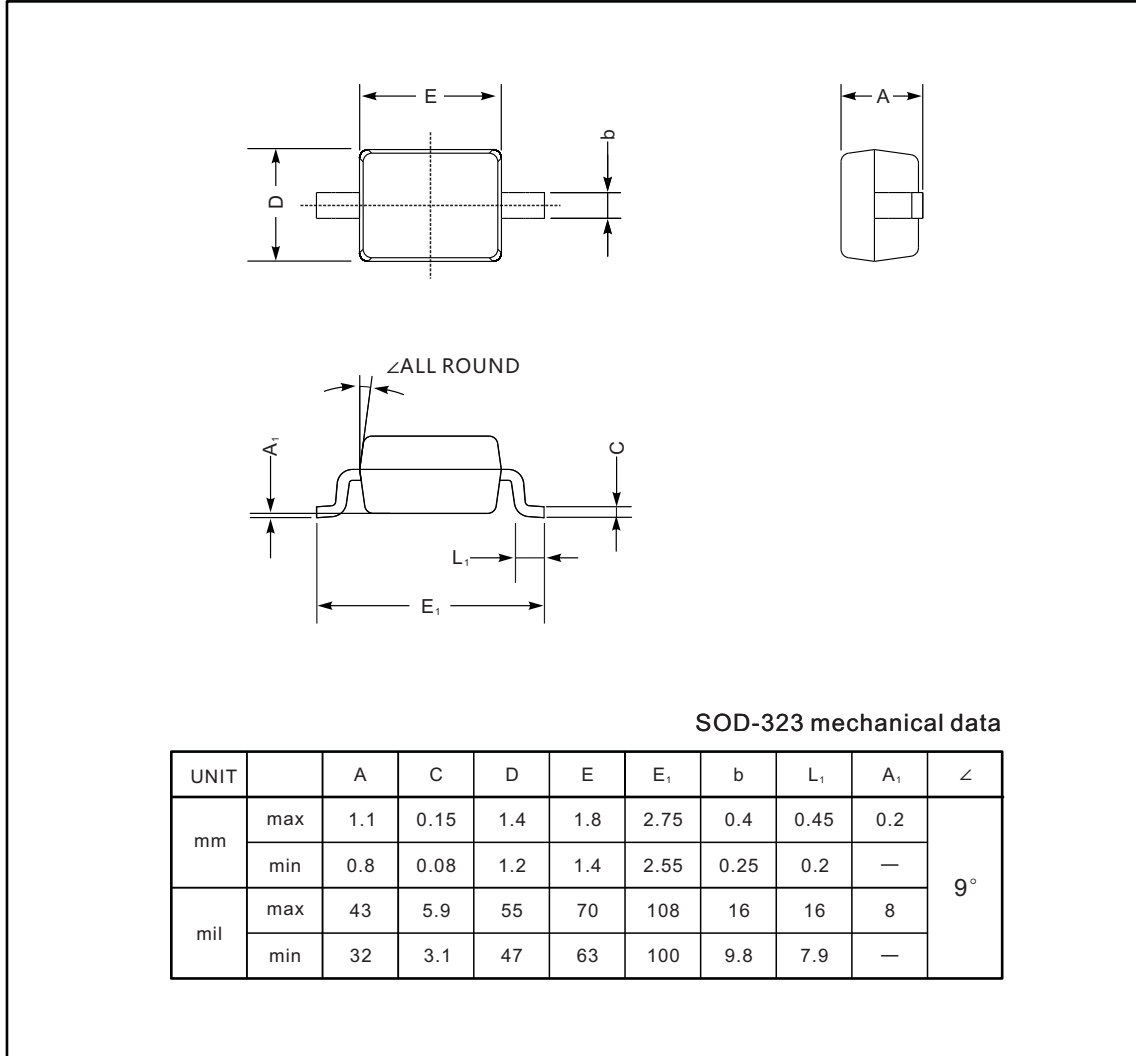
Fig.6 Typical Transient Thermal Impedance



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-323



The recommended mounting pad size

